



产品规格书

Product Name : Fast Acting Surface Mount Chip Fuse

AEM Part Number : F1206FA7000V024TM

Customer: 深圳宝龙达信息技术股份有限公司

Revision: 2

Date: 2011-11-09

AEM Components (Suzhou) Co., Ltd

458 Shenhu Road, Suzhou Industrial Park Jiangsu, P.R China, 215122 TEL: 86-512-6258-0028 FAX: 86-512-6258-0018

www.aemchina.com

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Prepared by	Checked by	Approved by	Accepted by customer			
Lingling Li	Yan Ma	Yan Ma	深圳宝龙达信息技术股份有限公司			
Signature						



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Fast Acting Surface Mount Chip Fuse

快断片式熔断器

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1 Operating Temperature Range

-55°℃ ~ **+125°**℃

2 Ratings

AEM Part Number	Current Rating (A)	Voltage Rating (VDC)	Nominal Cold DCR $(\Omega)^1$	
F1206FA7000V024TM	7.0	24	0.011	

1. Measured at ${\leqslant}10\%$ rated current and 25 $^\circ\!{\rm C}$ ambient.

3 Clear-Time Characteristics(Fast Acting):

% of current rating	Clear-time at 25 $^\circ\!\!\mathbb{C}$
100%	4 hours (min)
250%	5 seconds (max)
400%	0.05 seconds (max)

4 Interrupting Ratings:

7.0A 45A at rated voltages

5 Marking(Optional):

Black Marking Character Code

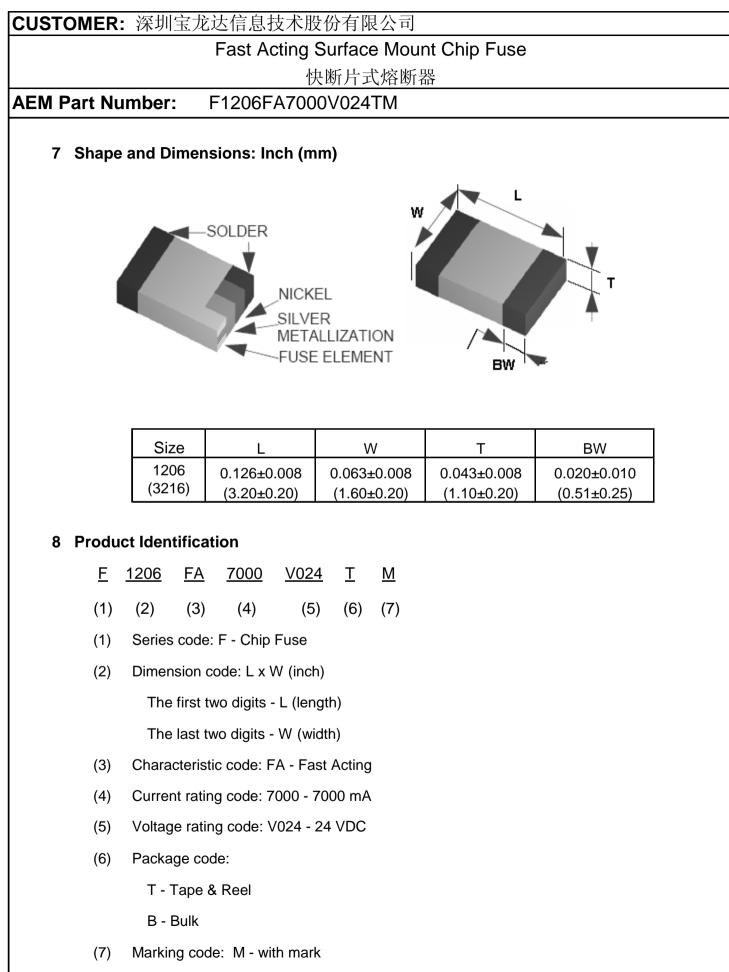
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6 Agency Approval:

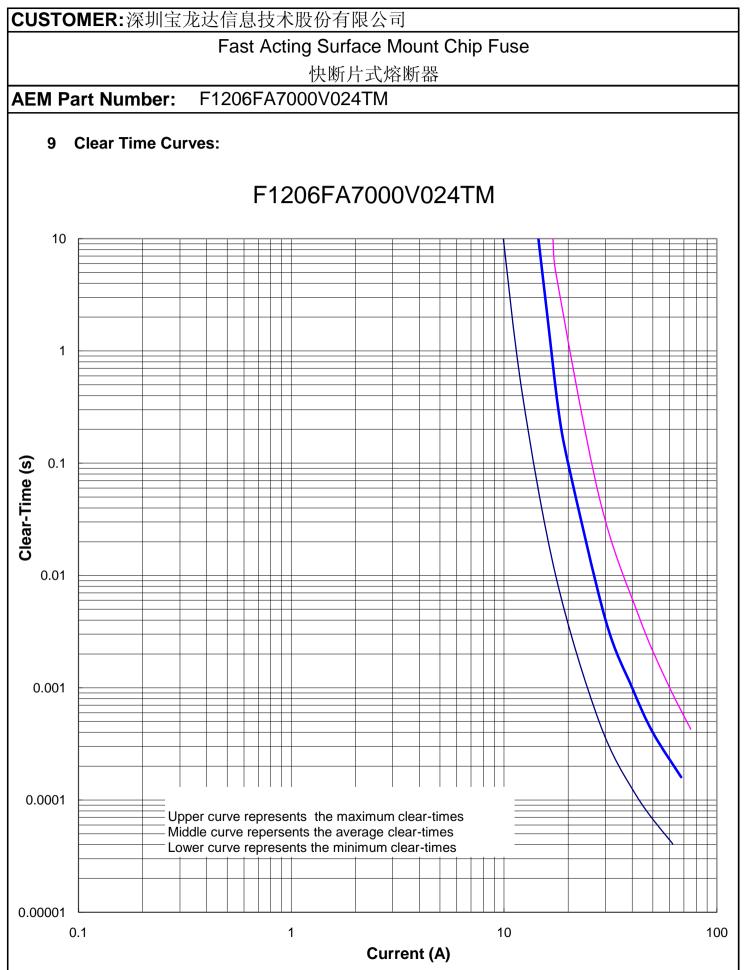
Recognized Under the Components Program of Underwriters Laboratories.

File Number: E232989

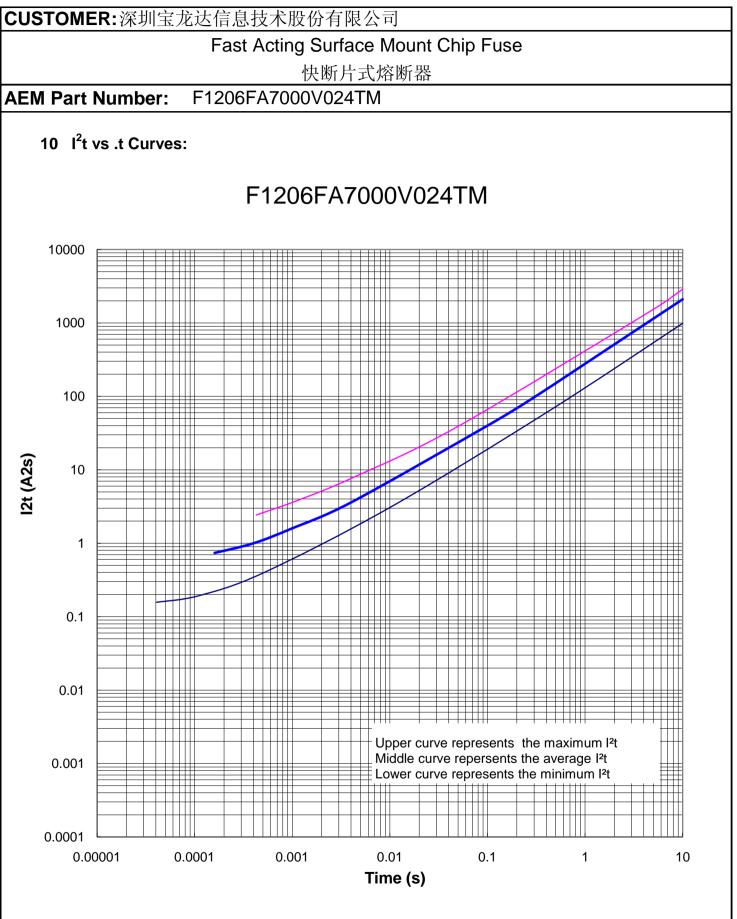














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11 Features

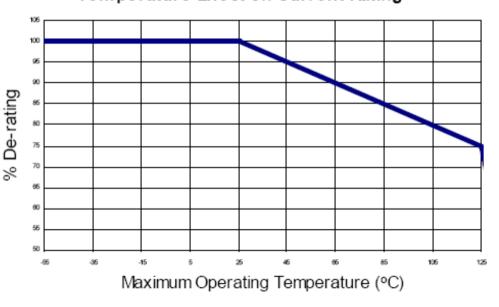
- 11.1 Mutilayer monolithic structure with glass ceramic body and silver fusing element
- 11.2 Silver termination with nickel and solder plating (lead free), providing excellent solderability
- 11.3 Compatible with both wave and reflow soldering processes

12 Typical Applications

- 12.1 Consumer Electronics, e.g. CD-/LD-Disc drives, portable sets (drives)
- 12.2 Communication Technology, e.g. ISDN-line card protection, PCM-cards, mobile phones tuner input, satellite receivers, cards in GSM-base stations
- 12.3 Data-Processing, e.g. disc drives, keyboard/mouse ports, LAN-/PC-cards, modems
- 12.4 Measurement and Control Technology, e.g. communication ports, measurement inputs/ probes/sensors, analysis units, PLCs
- 12.5 Medical Technology, e.g. communication ports, measurement in & out probes
- 12.6 Power Supply Technology, e.g. low voltage section of power-supplies/chargers

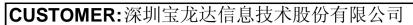
13 Temperature De-rating Guideline

The ambient temperature affects the current carrying capacity of fuses. When a fuse is operating at a temperature higher than 25° C, the fuse shall be "de-rated" according to the de-rating curve.



Temperature Effect on Current Rating





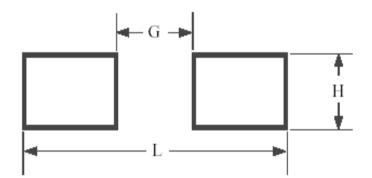
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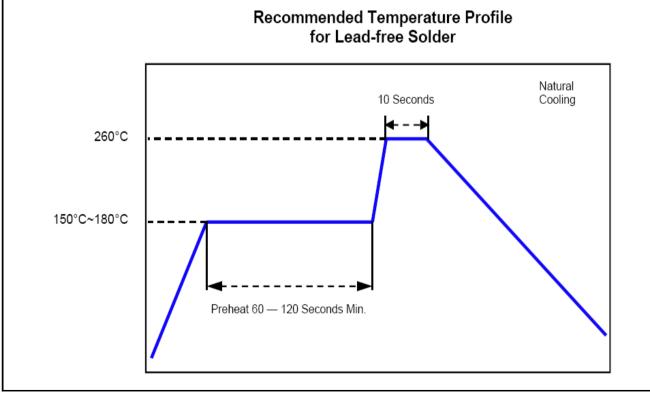
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14 Recommended PC Board Land Pattern

Chip Size	L	G	H	
	INCH (mm)	INCH (mm)	INCH (mm)	
1206 (3216)	0.173 (4.40)	0.059 (1.50)	0.071 (1.80)	



15 Recommended Temperature Profile for Reflow Soldering





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16 Special Measuring Equipment

16.1 Clear Time

Clear time is measured with clear time tester.

16.2 DC Resistance

DC resistance is measured with Keithley 580/Keithley 2010.

16.3 Interrupting Capability

Interrupting capability is measured with short circuit tester.

17 Reliability Tests

Reliability Test	Test Condition and Requirement
Bending	Board: 94x94x1.6 mm, 2 mm bend for 5 seconds, 20% DCR change max.
Solderability	255ºC, 5 seconds, 95% coverage min.
Soldering Heat Resistance	260ºC, 60 seconds, 10% DCR change max.
Terminal Strength	1206 – 1.5 kg 30 second hanging, no damage
Life	25ºC, 2000 hours, 80% rated current, no open circuit, voltage drop change≪±20%.
Thermal Shock	-65ºC to +125ºC, 100 cycles, no mechanical damage, 10% DCR change max.
Mechanical Vibration	5 – 3000 Hz, 0.4 inch double amplitude or 30 G peak, 10% DCR change max.
Mechanical Shock	1500 G, 0.5 milliseconds, half-sine shocks 10% DCR change max.
Salt Spray	5% salt solution, 48 hour exposure
Moisture Resistance	10 cycles, 15% DCR change max., no excessive corrosion



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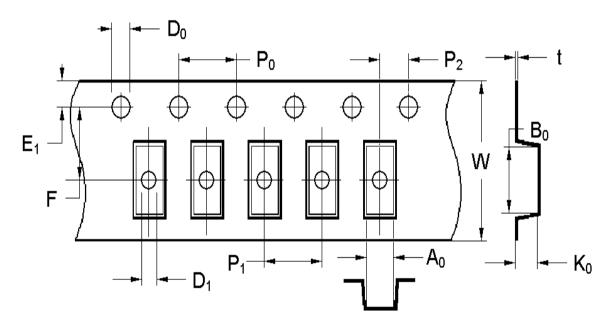
18 Packaging

18.1 Surface mount chip fuses are provided on tape-and-reel for use in pick-and-place

machines or in bulk for special applications. Both tape-and-reel and bulk products

are sealed in plastic bags with desiccant. The reel size is 7 inches.

18.2 Tape Dimensions: INCH (mm)



Size	Ao Bo Ko		Ko	Туре
1206	0.071 <u>+</u> 0.004	0.138 <u>+</u> 0.004	0.050 <u>+</u> 0.004	Plantia
(3216)	(1.80 <u>+</u> 0.10)	(3.50 <u>+</u> 0.10)	(1.27 <u>+</u> 0.10)	Plastic

E1	F	W	P1	P0	P2	D0	D1	t
0.069 <u>+</u> 0.004	0.138 <u>+</u> 0.002	0.315 <u>+</u> 0.004	0.157 <u>+</u> 0.004	0.157 <u>+</u> 0.004	0.079 <u>+</u> 0.002	0.059+0.004	0.039max	0.009 <u>+</u> 0.001
(1.75±0.10)	(3.50±0.05)	(8.00±0.10)	(4.00 <u>+</u> 0.10)	(4.00 <u>+</u> 0.10)	(2.00 <u>+</u> 0.05)	(1.50+0.10/-0.00)	(1.00max)	(0.23 <u>+</u> 0.02)



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18.3 Quantity Per Reel

Chip Size	Parts on 7 inch (178 mm) Reel	
1206 (3216)	3,000	

Other sizes and chip quantities can be provided upon customer's request.

19 Storage

- 19.1 The maximum ambient temperature shall not exceed 35 °C.
 Storage temperature higher than 35°C could result in the deformation of packaging materials.
- 19.2 The maximum relative humidity recommended for storage is 75%. High humidity with high temperature could accelerate the oxidation of the solder plating on the termination and reduce the solderability of the components.
- 19.3 Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- 19.4 The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.